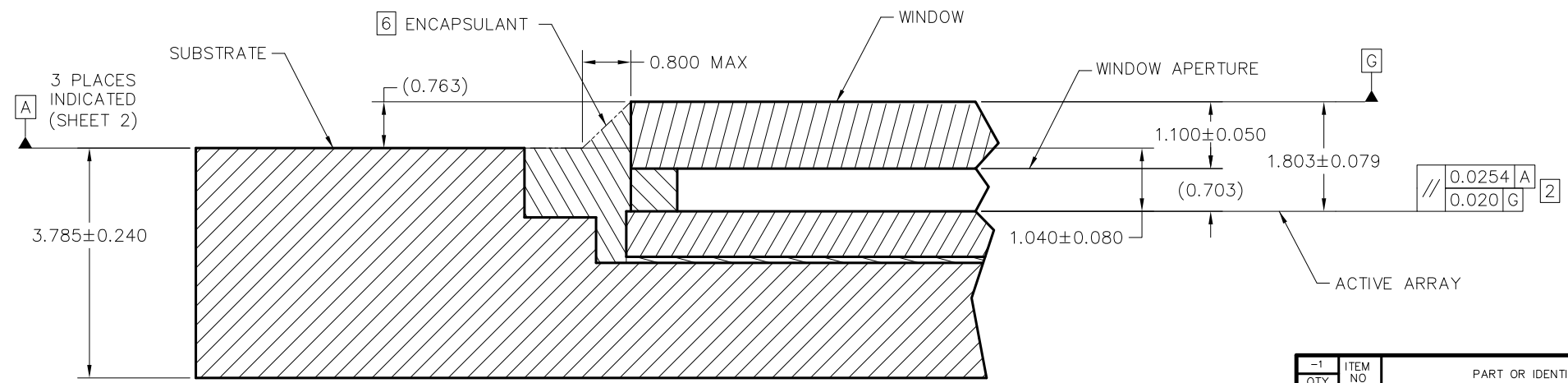
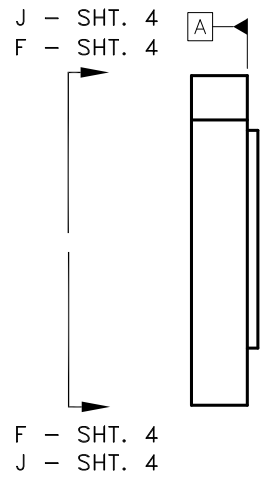
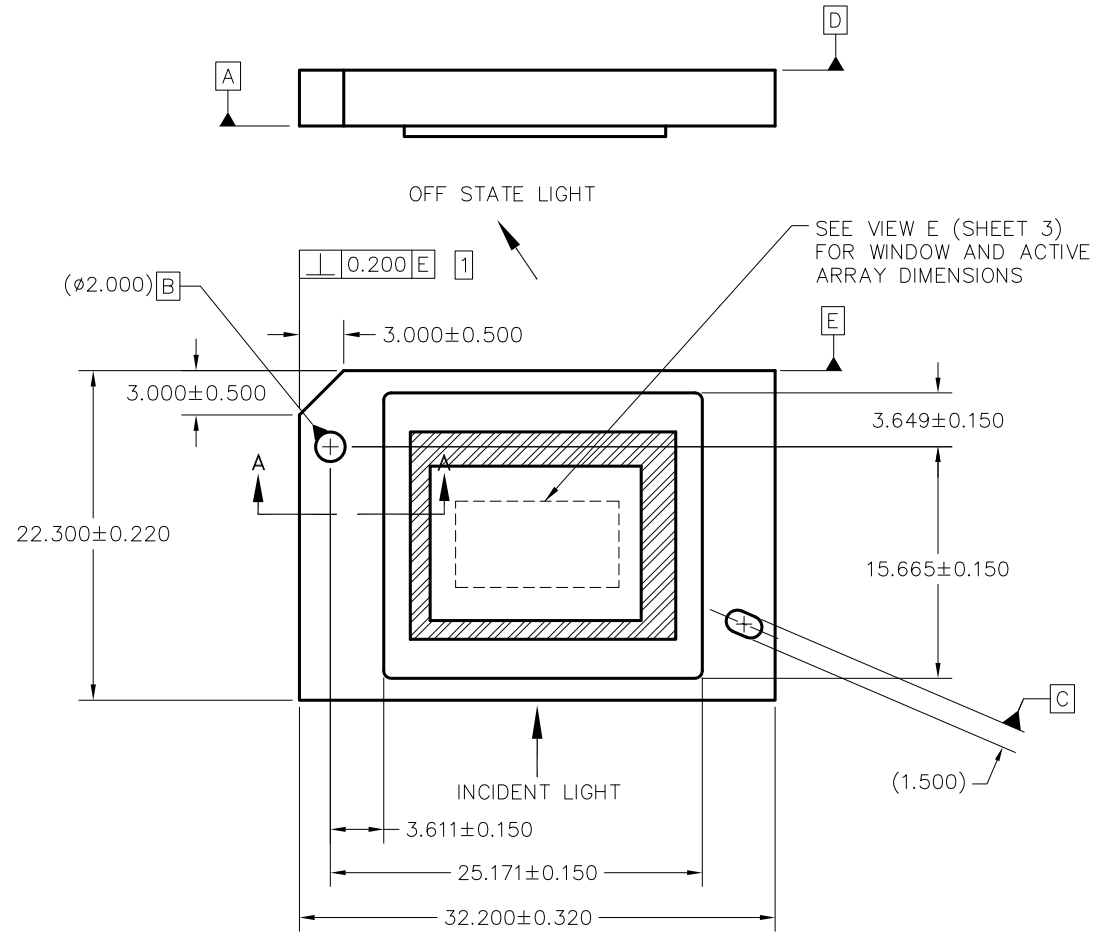


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2159769, INITIAL RELEASE	07/28/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA TO THE LEFT OF THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA TO THE RIGHT OF THE SYMBOLIZATION PAD.

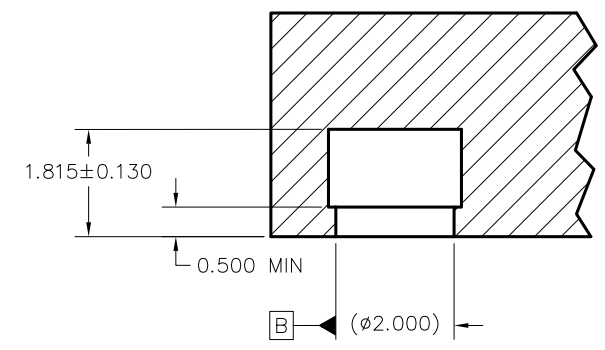


SECTION A-A
SCALE 20/1

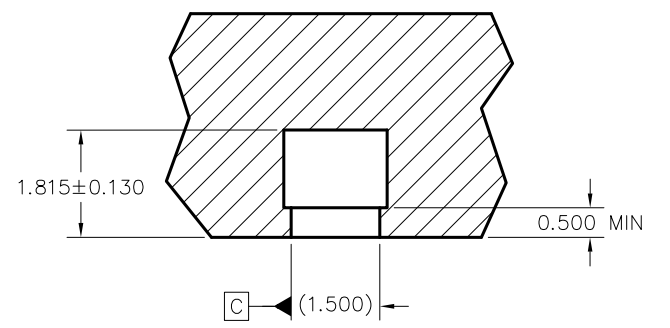
-1 QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES								
PARTS LIST												
		DWN F. ARMSTRONG	DATE 07/12/16	<table border="1"> <tr> <td colspan="2" style="text-align: center;">TEXAS INSTRUMENTS <i>Dallas, Texas</i></td> </tr> <tr> <td colspan="2" style="text-align: center;">ICD, MECHANICAL, DMD .49" DC2K MTRP 2xLVDS HB SERIES 410 (FXF PACKAGE)</td> </tr> <tr> <td>SIZE B</td> <td>DRAWING NO 2515166</td> </tr> <tr> <td>SCALE 4/1</td> <td>REV A</td> </tr> </table>	TEXAS INSTRUMENTS <i>Dallas, Texas</i>		ICD, MECHANICAL, DMD .49" DC2K MTRP 2xLVDS HB SERIES 410 (FXF PACKAGE)		SIZE B	DRAWING NO 2515166	SCALE 4/1	REV A
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SIZE B	DRAWING NO 2515166											
SCALE 4/1	REV A											
		ENGR F. ARMSTRONG	07/12/16									
		QA P. KONRAD	08/03/16									
		COE M. DORAK	08/03/16									
		NONE	0314DA									
		NEXT ASSY	USED ON									
		APPLICATION										

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES: ANGLES ± 1°
2 PLACE DECIMALS ±0.25
3 PLACE DECIMALS ±0.50
REMOVE ALL BURRS AND SHARP EDGES
INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994
DIMENSIONAL LIMITS APPLY BEFORE PROCESSES
PARENTHEICAL INFO FOR REF ONLY

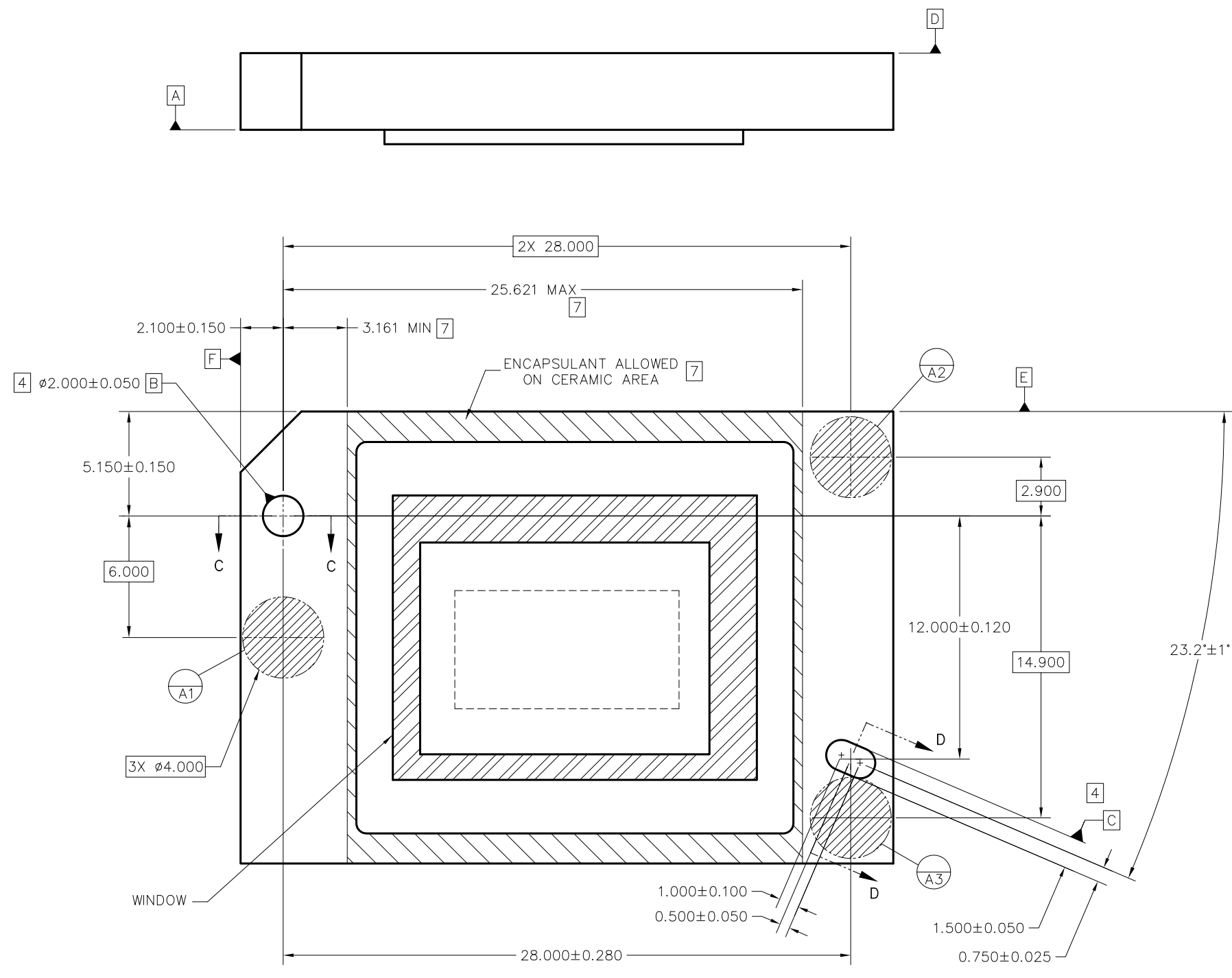




SECTION C-C
DATUM B
SCALE 16/1



SECTION D-D
DATUM C
SCALE 16/1



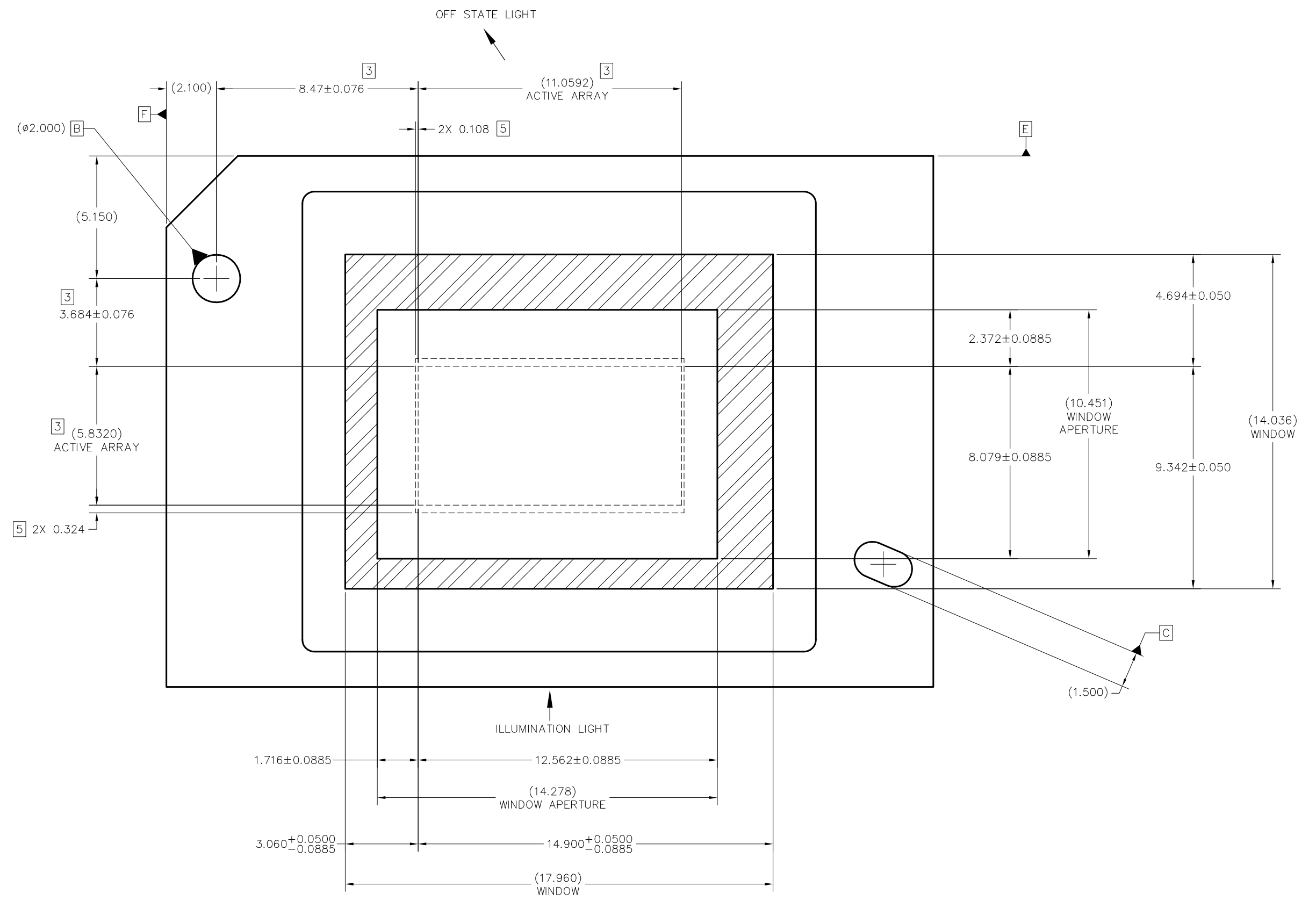
VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1

D

C

B

A



VIEW E (SHEET 1)
DMD WINDOW AND ACTIVE ARRAY
SCALE 12:1

8

7

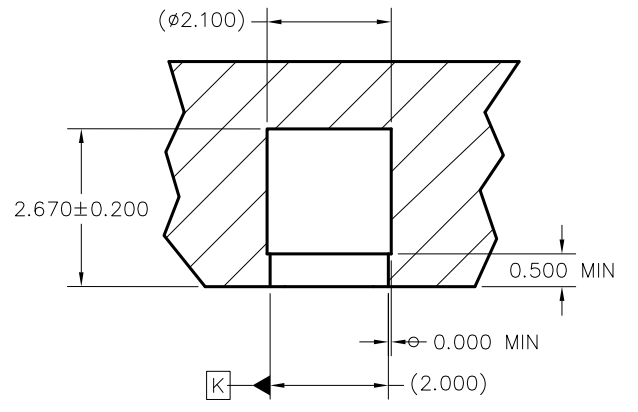
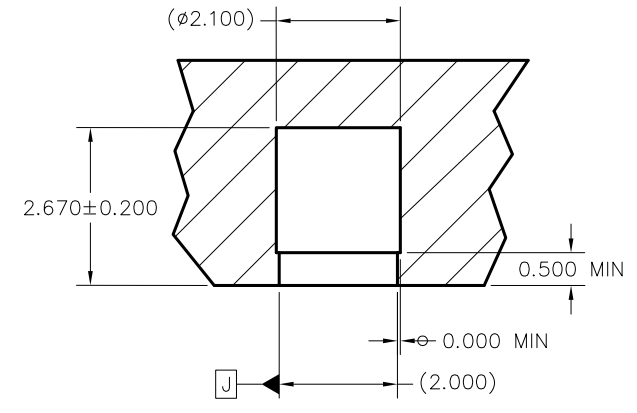
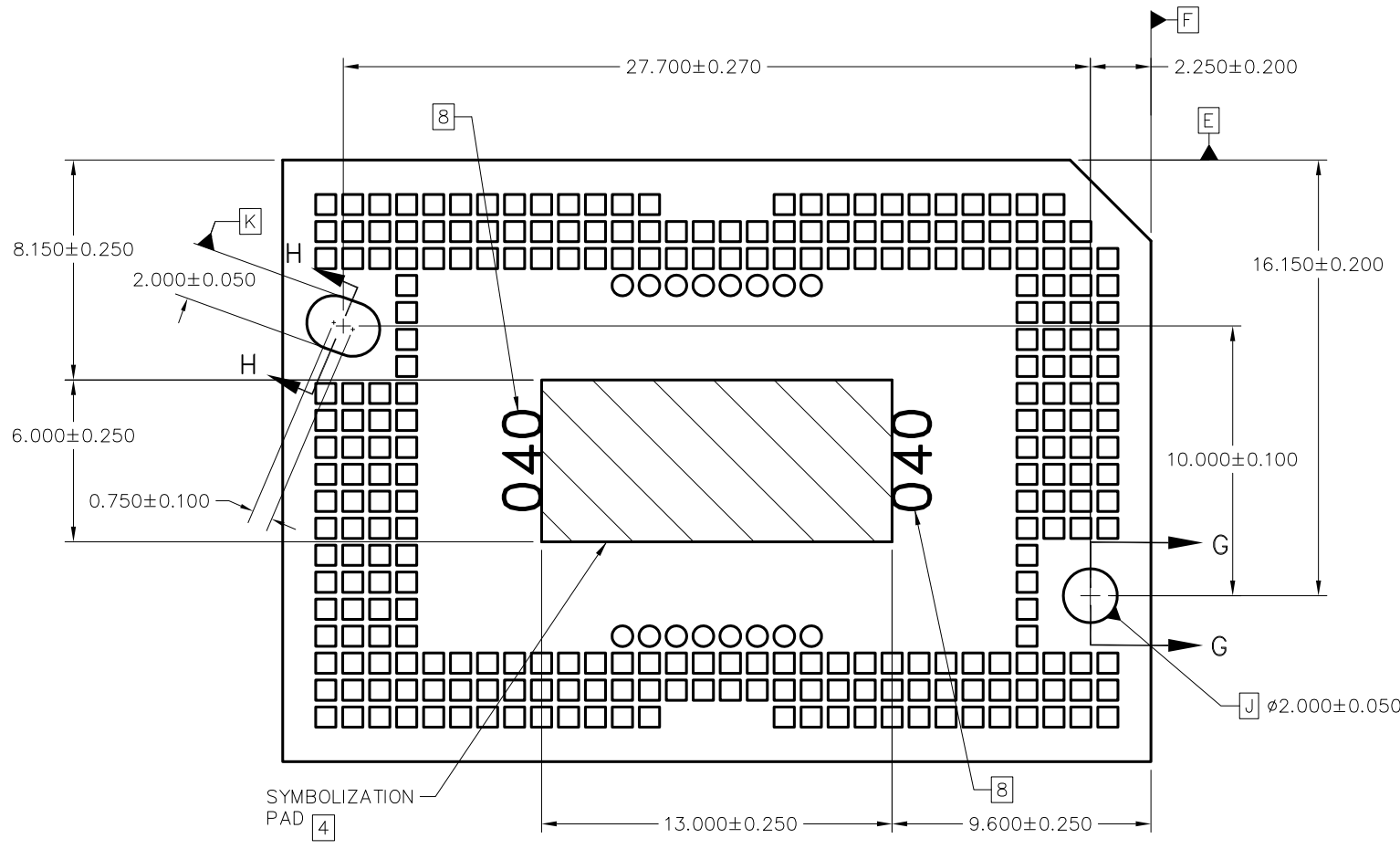
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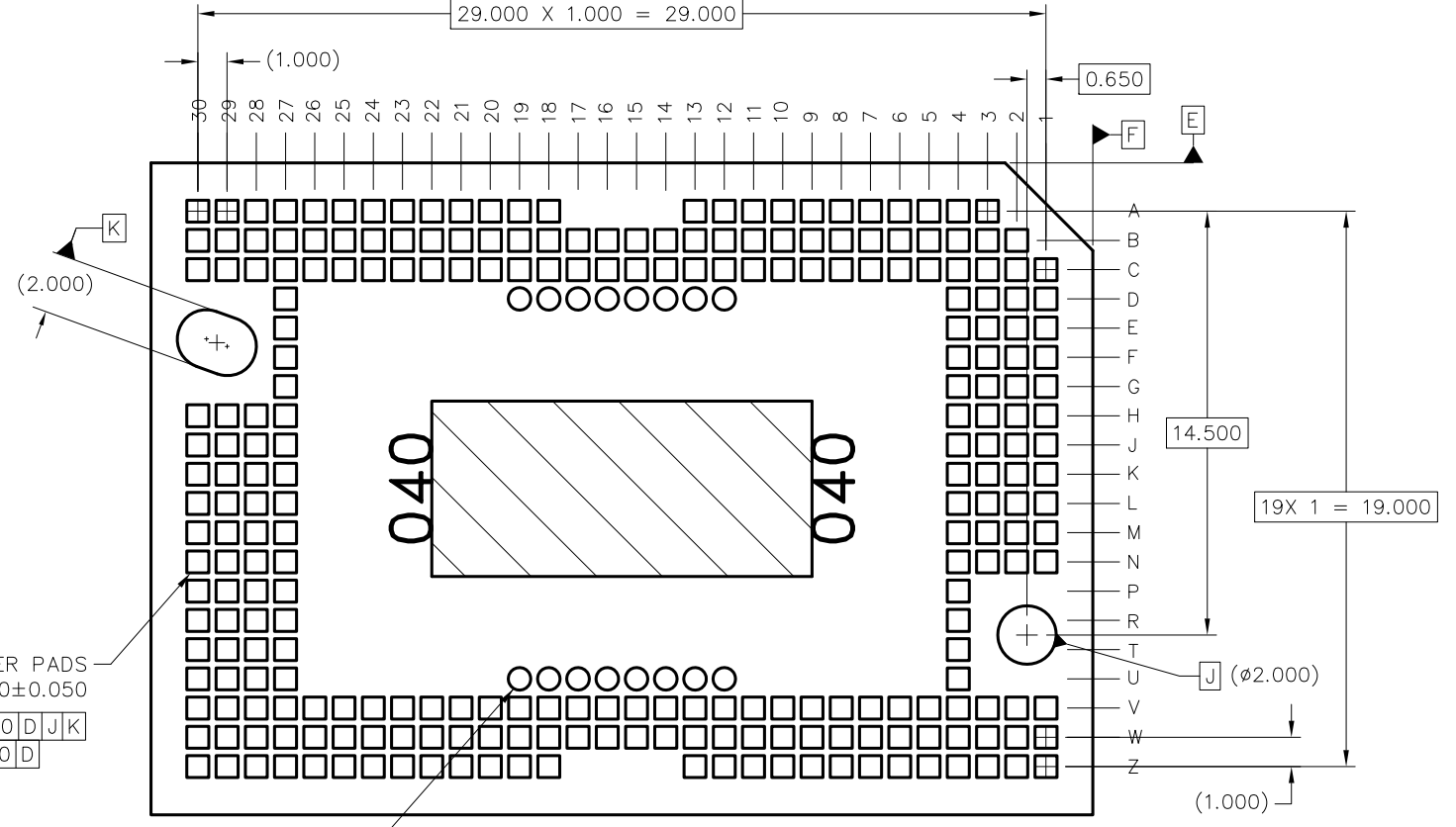
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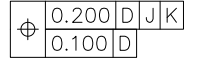
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VIEW F-F (SHEET 1)
DATUMS J AND K, SYMBOLIZATION PAD
SCALE 8/1



257X LGA CUSTOMER PADS
0.750±0.050 X 0.750±0.050



16X LGA TEST PADS
DO NOT CONNECT

VIEW J-J (SHEET 1)
LGA PADS
SCALE 8/1

8

7

6

5

4

3

2

1

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